

Part Number: KP-2012SEC SUPER BRIGHT ORANGE

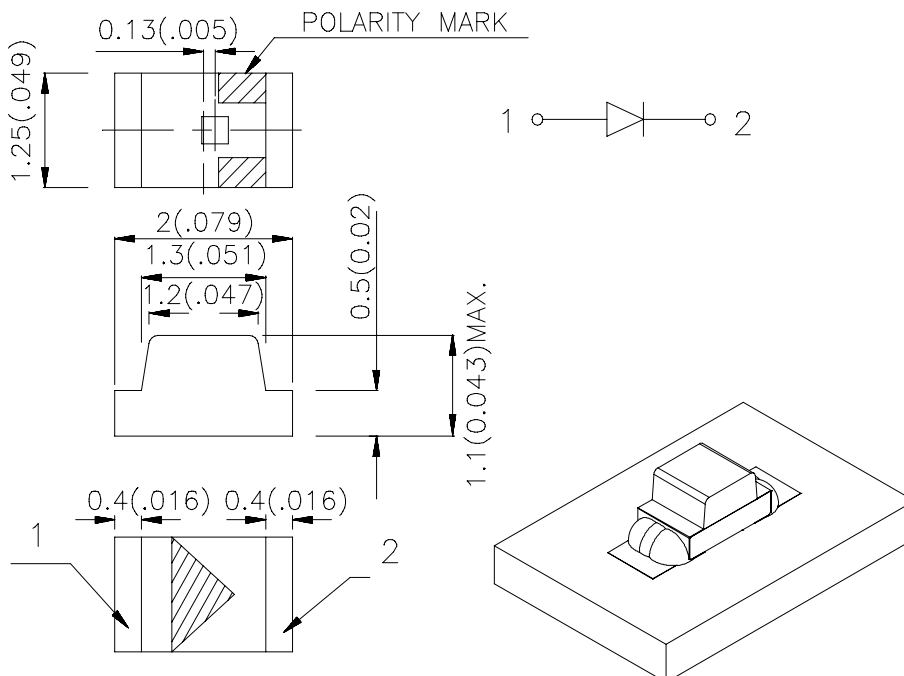
Features

- 2.0mmx1.25mm SMT LED,1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

Description

The Super Bright Orange device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KP-2012SEC	SUPER BRIGHT ORANGE (InGaAlP)	WATER CLEAR	70	200	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity / luminous flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λ_D [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
C	Capacitance	Super Bright Orange	30		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.0	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR = 5V

Notes:

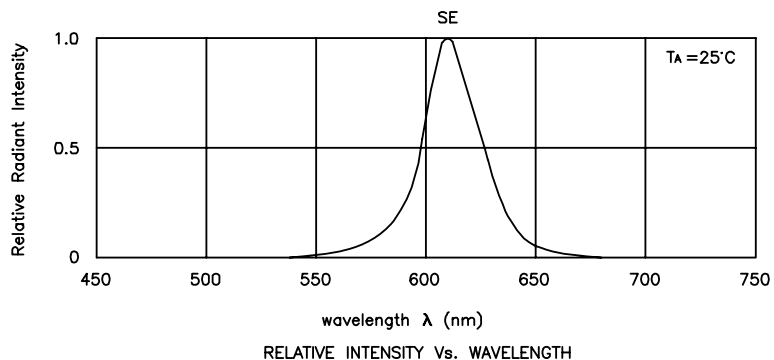
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	75	mW
Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

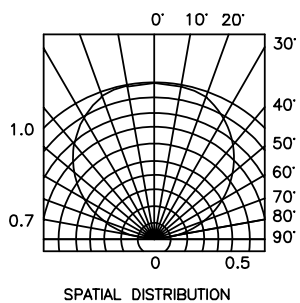
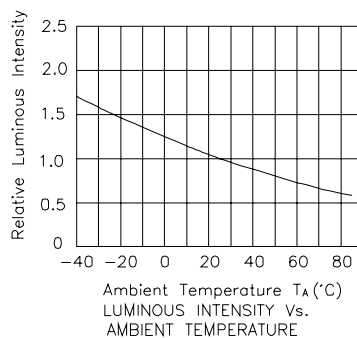
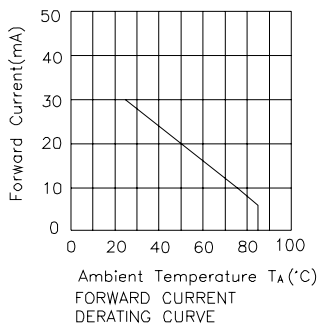
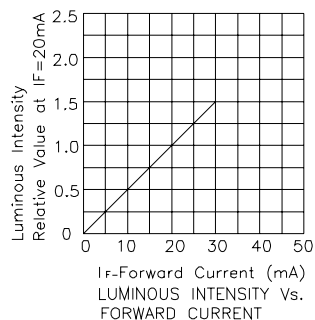
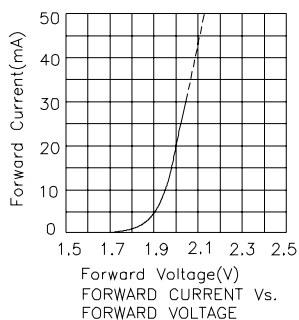
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



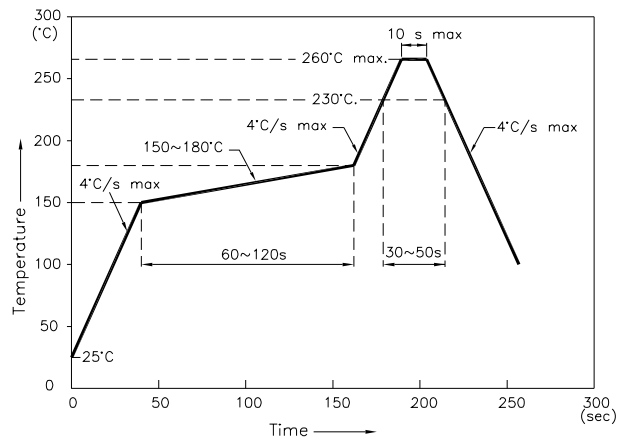
Super Bright Orange

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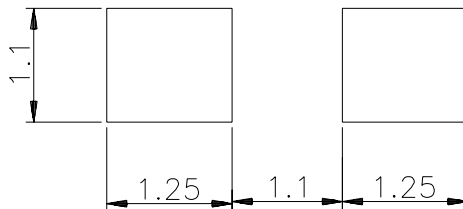
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

**Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)**



**Tape Specifications
(Units : mm)**

